



## Corres. and Mail

AMENDMENT UNDER 37 C.F.R. § 1.116 EXPEDITED PROCEDURE GROUP 1775 PATENT APPLICATION

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q67726

RECEIVED

Mitsuo OSADA, et al.

MAR 09 2004

Appln. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: LAVILLA, MICHAEL E

Filed: December 13, 2001

For:

MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC

PACKAGE USING THE SAME

## AMENDMENT UNDER 37 C.F.R. § 1.116

## **MAIL STOP AF**

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated December 5, 2003, please amend the aboveidentified application as follows on the accompanying pages.

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